

AMENDMENTS TO THE CLAIMS

1-16. (Cancelled)

17. (Previously presented) A laminate, comprising a substrate, either a magnetic film provided on top of said substrate, or said magnetic film and a metallic oxidation prevention film provided thereon, and a resist layer formed from a positive resist composition on top of either said magnetic film or said magnetic film and said metallic oxidation prevention film provided thereon, wherein said positive resist composition comprises:
a resin component (A'), which exhibits increased alkali solubility under action of acid, and comprises a structural unit (a1) represented by a general formula (I) shown below:



... (I)

(wherein, R represents -H or -CH₃), and

a structural unit (a2) represented by a general formula (II) shown below:



... (II)

(wherein, R represents -H or -CH₃, and X represents an acid dissociable, dissolution inhibiting group, which is an alkyl group with a tertiary carbon atom in which said tertiary carbon atom is bonded to an ester group),

a diazomethane-based acid generator (B1), and

an onium salt-based acid generator (B2).

18. (Original) A laminate according to claim 17, wherein a principal component of said magnetic film comprises one or more metals selected from a group consisting of iron, cobalt, and nickel.

19. (Original) A laminate according to claim 17, wherein a principal component of said oxidation prevention film comprises one or more materials selected from a group consisting of tantalum and aluminum oxide (Al_2O_3).

20. (Currently amended) A method for forming a resist pattern, comprising the steps of: (1) providing a resist layer formed from a positive resist composition, either on top of a substrate and a magnetic film provided on top of said substrate, or on top of a metallic oxidation prevention film provided on top of said magnetic film, (2) conducting selective exposure of said resist layer, (3) performing post exposure baking of said selectively exposed resist layer, and (4) conducting alkali developing of said post exposure baked resist layer, wherein said positive resist composition comprises:

a resin component (A'), which exhibits increased alkali solubility under action of acid, and comprises a structural unit (a1) represented by a general formula (I) shown below:



(wherein, R represents -H or -CH₃), and

a structural unit (a2) represented by a general formula (II) shown below:



(wherein, R represents -H or -CH₃, and X represents an acid dissociable, dissolution inhibiting group, which is an alkyl group with a tertiary carbon atom in which said tertiary carbon atom is bonded to an ester group),

a diazomethane-based acid generator (B1), and

an onium salt-based acid generator (B2 (B2)).

21. (Original) A method for forming a resist pattern according to claim 20, wherein a material in which a principal component comprises one or more metals selected from a group consisting of iron, cobalt, and nickel is used as said magnetic film.

22. (Original) A positive resist composition according to claim 20, wherein a material in which a principal component comprises one or more materials selected from a group consisting of tantalum and aluminum oxide (Al₂O₃) is used as said oxidation prevention film.